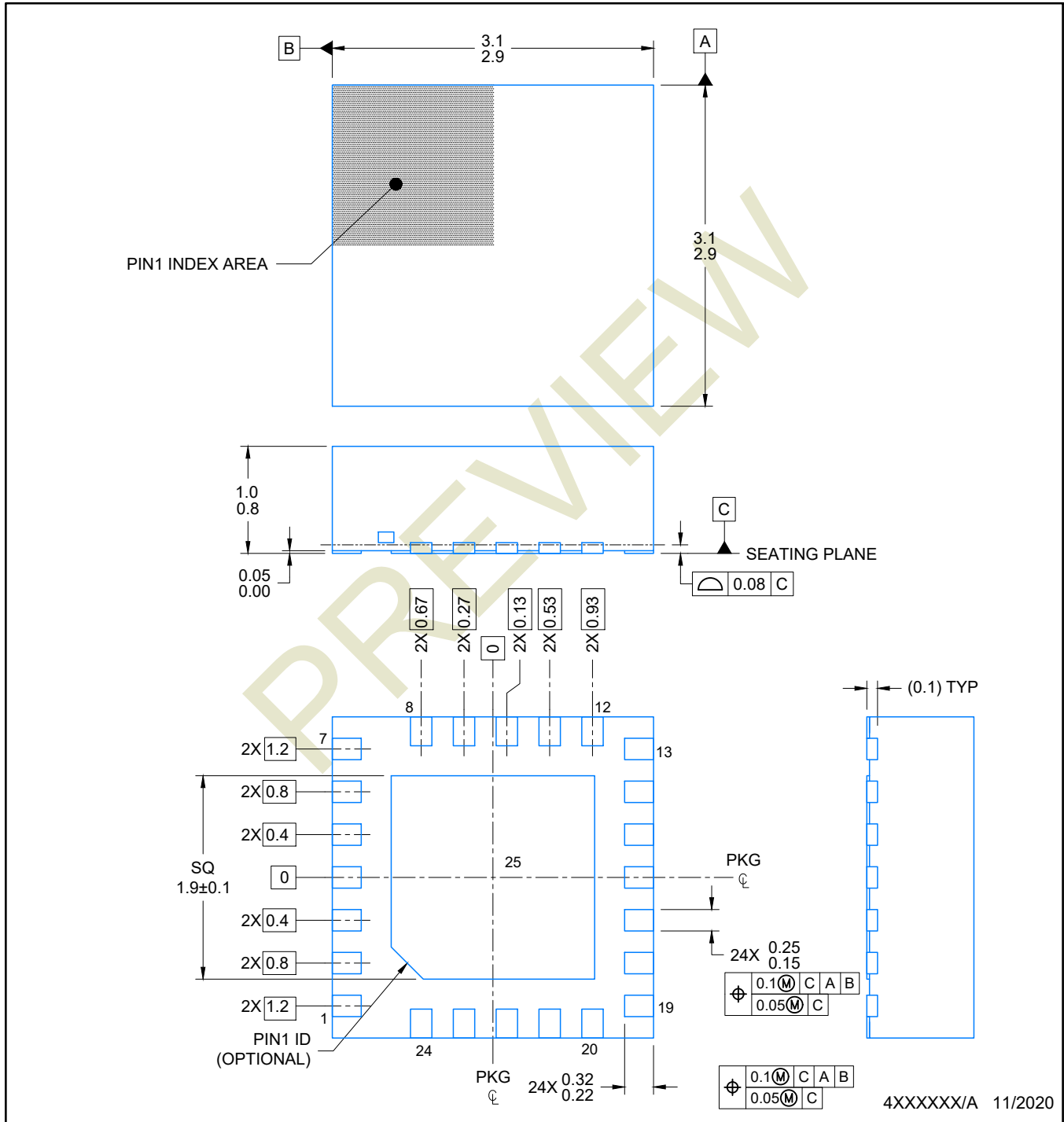


PREVIEW

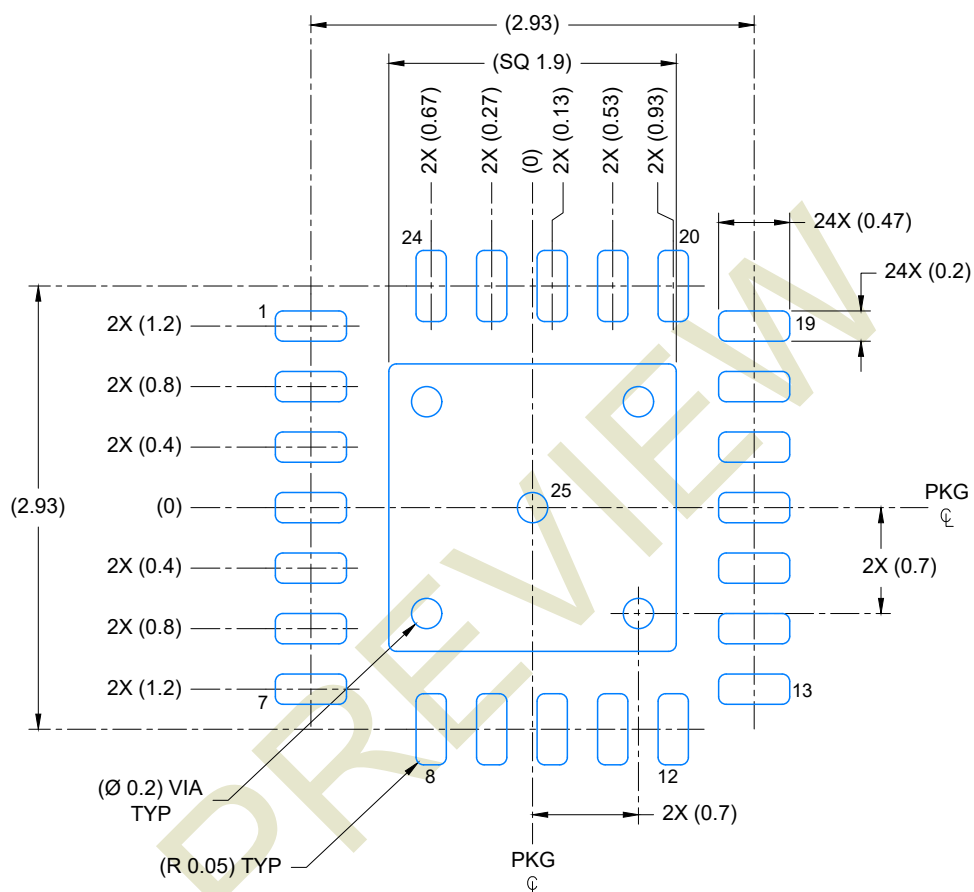
DATA BOOK
PACKAGE OUTLINE

DRAFTSMAN: F.LASTNAME		DATE: MM/DD/YYYY			DIMENSIONS IN MILLIMETERS		
DESIGNER: F.LASTNAME		DATE: MM/DD/YYYY	 TEXAS INSTRUMENTS SEMICONDUCTOR OPERATIONS		CODE IDENTITY NUMBER 01295		
CHECKER: F.LASTNAME		DATE: MM/DD/YYYY					
ENGINEER: F.LASTNAME		DATE: MM/DD/YYYY	ePOD, OUTLINE / PKGGRP, XX PIN, X.X MM PITCH				
APPROVED: F.LASTNAME		DATE: MM/DD/YYYY					
RELEASED: F.LASTNAME		DATE: MM/DD/YYYY					
TEMPLATE INFO: EDGE# 4218519		DATE: 12/14/2018	SCALE NTS	SIZE A	4XXXXXXX	REV A	PAGE 1 OF 5



NOTES:

1. All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.
3. The package thermal pad must be soldered to the printed circuit board for optimal thermal and mechanical performance.

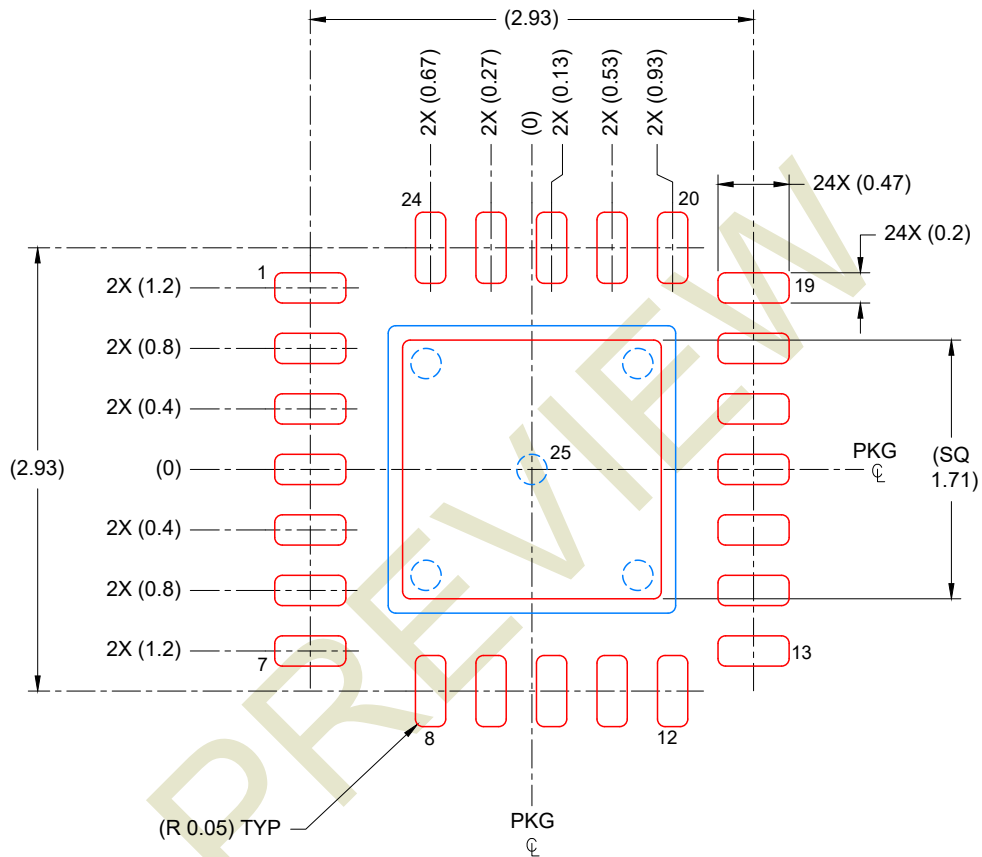


LAND PATTERN EXAMPLE
EXPOSED METAL SHOWN
SCALE: 20X

4XXXXXX/A 11/2020

NOTES: (continued)

- This package is designed to be soldered to a thermal pad on the board. For more information, see Texas Instruments literature number SLUA271 (www.ti.com/lit/sluea271).
- Vias are optional depending on application, refer to device data sheet. If any vias are implemented, refer to their locations shown on this view. It is recommended that vias under paste be filled, plugged or tented.



SOLDER PASTE EXAMPLE
 BASED ON 0.125 mm THICK STENCIL

EXPOSED PAD
 81% PRINTED COVERAGE BY AREA
 SCALE: 20X

4XXXXXX/A 11/2020

NOTES: (continued)

6. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.

REVISIONS				
REV	DESCRIPTION	ECR	DATE	ENGINEER / DRAFTSMAN
A	RELEASE NEW DRAWING	XXXXXXX	MM/DD/YYYY	F.LASTNAME / F.LASTNAME
PREVIEW				
SCALE		SIZE	4XXXXXX	
NTS		A	A	
			5 OF 5	